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Dimensions

Chip Size	0805
L	2.01mm +0.3/-0.25mm (0.079 in +0.012/-0.01 in)
W	1.27mm +0.3/-0.25mm (0.05 in +0.012/-0.01 in)
T	1.57mm MAX (0.062 in MAX)
B	0.51mm +/-0.25mm (0.02 in +/-0.01 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	100

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
Termination	Solder Plated
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	8200 pF
Capacitance Tolerance	5%
Voltage DC	6.3 VDC
Dielectric Withstanding Voltage	15.75 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	60.98 GOhms

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